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APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/965,253	09/26/2001		Jeffrey Johnson	42390P12455	3010	
8791	7590	05/06/2004		EXAM	EXAMINER	
		OFF TAYLOR &	NGUYEN	NGUYEN, DANNY		
12400 WILSHIRE BOULEVARD, SEVENTH FLOOR LOS ANGELES, CA 90025				ART UNIT	PAPER NUMBER	
LOS ANGLI	Lo, CA	70023		2836		

DATE MAILED: 05/06/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

•		Application No.	Applicant(s)	
	·	09/965,253	JOHNSON, JEFFREY	
	Office Action Summary	Examiner	Art Unit	
		Danny Nguyen	2836	Au Au
Period fo	The MAILING DATE of this communica	ation appears on the cover sheet w	ith the correspondence ac	idress
A SHO THE I - Exter after - If the - If NO - Failur Any r	ORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNIC, isions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this commun period for reply specified above is less than thirty (30) period for reply is specified above, the maximum stature to reply within the set or extended period for reply will eply received by the Office later than three months after that term adjustment. See 37 CFR 1.704(b).	ATION. 37 CFR 1.136(a). In no event, however, may a lication. days, a reply within the statutory minimum of thi tory period will apply and will expire SIX (6) MOI II, by statute, cause the application to become A	reply be timely filed rty (30) days will be considered timel NTHS from the mailing date of this c BANDONED (35 U.S.C. § 133).	ly. communication.
Status				
2a)☐ 3)☐	Responsive to communication(s) filed This action is FINAL . 2b Since this application is in condition fo closed in accordance with the practice)⊠ This action is non-final. r allowance except for formal mat	• •	e merits is
Dispositi	on of Claims			
5)□ 6)⊠ 7)□	Claim(s) <u>1-30</u> is/are pending in the apple 4a) Of the above claim(s) is/are Claim(s) is/are allowed. Claim(s) <u>1-30</u> is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction	withdrawn from consideration.		
Applicati	on Papers			
10) 🔲 -	The specification is objected to by the I The drawing(s) filed on is/are: a Applicant may not request that any objection Replacement drawing sheet(s) including the oath or declaration is objected to be	a) accepted or b) objected to on to the drawing(s) be held in abeya ne correction is required if the drawing	nce. See 37 CFR 1.85(a). g(s) is objected to. See 37 Cl	
Priority u	nder 35 U.S.C. § 119			
a)[ocuments have been received. Ocuments have been received in A the priority documents have beer al Bureau (PCT Rule 17.2(a)).	Application No received in this National	Stage
2) Notice 3) Inform	e of References Cited (PTO-892) of Oraftsperson's Patent Drawing Review (PTO- nation Disclosure Statement(s) (PTO-1449 or PTO- No(s)/Mail Date	D-948) Paper No(Summary (PTO-413) (s)/Mail Date Informal Patent Application (PTC 	O-152)

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 01/02/2004 has been entered.

Response to Arguments

2. Applicant's arguments with respect to claims1, 11, and 21 have been considered but are most in view of the new ground(s) of rejection.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1, 2, 5-7, 9-12, 15-17, 19-22, 25-27, 29, 30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yue et al. (USPN 6,509,779) in view of Ker (USPN 5,901,022).

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Regarding claims 1, 10, 11, 20, Yue discloses a method and an apparatus (see figures 3 and 4) comprises an inductor (110) having an impedance connected in series between an output of a high frequency circuit (20) operating at a frequency and an ESD circuit (40) configured to protect the high frequency circuit from an ESD event, the impedance having substantially high value at that frequency and a substantially low value at the ESD event (e.g. col. 3 and 4, lines 63-4). Yue does not disclose an ESD clamping circuit as claimed. Ker discloses an ESD protection circuit (e.g. see fig. 8) comprises an ESD clamp circuit (500) is connected to an inductor (L) via an ESD circuit (400) to protect electrostatic discharge phenomena. It would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified to the ESD protection circuit of Yue to incorporate the ESD clamping circuit as taught by Ker in order to protect IC circuit against ESD damage (col. 1, lines 20-26).

Regarding claims 21, 30, Yue discloses a circuit (such as fig. 3 and 4) comprises a high frequency circuit operating at a frequency (e.g. 100), the high frequency circuit having an output (20); an electrostatic discharge ESD circuit (40) configured to protect the high frequency circuit from an ESD event (col. 4, lines 9-15); an inductor (110) having an impedance connected in series between an output of a high frequency circuit (20) operating at a frequency and an ESD circuit (40) configured to protect the high frequency circuit from an ESD event, the impedance having substantially high value at that frequency and a substantially low value at the ESD event (e.g. col. 3 and 4, lines 63-4). Yue does not disclose an ESD clamping circuit as claimed. Ker discloses an ESD protection circuit (e.g. see fig. 8) comprises an ESD clamp circuit (500) is connected to

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an inductor (L) via an ESD circuit (400) to protect electrostatic discharge phenomena. It would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified to the ESD protection circuit of Yue to incorporate the ESD clamping circuit as taught by Ker in order to protect IC circuit against ESD damage (col. 1, lines 20-26).

Regarding claims 2, 12, 22, Yue discloses the ESD circuit (40) has first and second terminals, the first terminal being connected to one end on the inductor (110), and the second terminal being connected to ground (shown in fig. 3).

Regarding claims 5, 15, 25, Yue et al. disclose the inductor is connected between a first bond pad (10) of the output and a second bond pad (10a) of the ESD circuit (40) on a package substrate in a package encapsulating the high frequency circuit (100d) and the ESD circuit (40) (see fig. 13).

Regarding claims 6, 16, 26, Yue discloses connecting the inductor (110) comprise connecting one end of the inductor to the first bond pad (10) via a first bond wire; and connecting an other end of the inductor to the second bond pad (10a) via a second bond wire.

Regarding claims 9, 19, 29, Yue discloses the high frequency higher than 1 gigahertz (col. 4, lines 24-25).

Regarding claim 7, 17, 27, Yue et al. disclose the high frequency circuit and ESD circuit are on a silicon die mounted on the package substrate (see abstract).

4. Claims 3, 4, 13, 14, 23, 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yue in view of Ker, and further in view of Kleveland et al (USPN

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5,969,929). Yue and Ker do not disclose the ESD circuit is a gate grounded NMOS and a diode. Kleveland discloses an ESD circuit being a gate grounded NMOS (such as 330 shown in fig. 3B) and an ESD circuit being a diode (116 shown in fig. 1). It would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the ESD circuit of Yue and Ker with a GGNMOS and a diode as taught by Kleveland in order to protect ESD event (col. 5, lines 49-53).

5. Claims 8, 18, 28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yue et al in view of Young et al, and further in view of Chiu (USPN 6,414,849). Yue and Ker do not disclose the package is flip-chip BGA package. Chiu discloses the package is flip-chip BGA package (col. 5, line 35). It would have been obvious to one of ordinary skill in the art at the time the invention was made to have modified the integrated circuit of Yue and Ker to use a flip-chip BGA package as taught by Chiu in order to reduce stress in the IC circuit (Chiu, col. 5, lines 48-51).

Conclusion

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Danny Nguyen whose telephone number is (571)-272-2054. The examiner can normally be reached on Mon to Fri 8:00 AM to 4:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Brian Sircus can be reached on (571)-272-2058. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Business Center (EBC) at 866-217-9197 (toll-free).

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic

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4/27/2004

BRIAN SIRCUS

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